

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Serial No.: Herewith

Filed: Herewith

Inventor: Takahiro Iijima et al

For: Method of Production of Semiconductor Package

Atty Doc. No.: 188-03

PRELIMINARY AMENDMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Please amend the title as shown on the marked-up copies each of pages 1 and 13 of the specification to read as follows:

METHOD OF PRODUCTION OF SEMICONDUCTOR PACKAGE

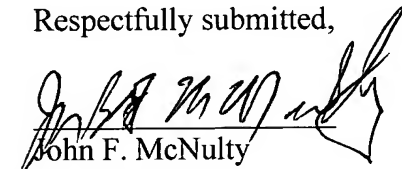
Please amend the specification and claims as follows.

In the specification:

Page 1 prior to "Background of the Invention", add the headline "Cross-Reference To Related Applications" and its paragraph as shown on the enclosed sheet 2.

Please amend the claims as shown on the enclosed sheet 3.

Respectfully submitted,



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Cross-Reference to Related Applications

This application is a divisional of US Patent Application No. 10/281,791 filed October 28, 2002.